MLCC Tin/Lead Termination "B" (LD Series)

COG (NP0) - General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

See FLEXITERM® section for CV options

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.



available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.



COG (NP0) - Specifications and Test Methods

Paramet	ter/Test	NP0 Specification Limits	Measuring	Conditions					
Operating Tem	perature Range	-55°C to +125°C	Temperature C	Cycle Chamber					
Сарас	itance	Within specified tolerance	Freq.: 1.0 MHz ± 10	% for cap ≤ 1000 pF					
C	2	<30 pF: Q≥ 400+20 x Cap Value ≥30 pF: Q≥ 1000	i.0 kHz ± 10% fc Voltage: 1.0	Wrms ± .2V					
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 60 ± 5 secs @ roo						
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device wit for 500V	and discharge current 0 mA (max) h 150% of rated voltage					
	Appearance	No defects	Deflectio						
Resistance to Flexure	Capacitance Variation	$\pm 5\%$ or $\pm .5$ pF, whichever is greater	Test Time: 30 seconds						
Stresses	Q	Meets Initial Values (As Above)							
	Insulation Resistance	≥ Initial Value x 0.3	90 mm						
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.						
	Appearance	No defects, <25% leaching of either end terminal							
	Capacitance Variation	\leq ±2.5% or ±.25 pF, whichever is greater		adder at 26000 for 60					
Resistance to Solder Heat	Q	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 3						
Soluei Heat	Insulation Resistance	Meets Initial Values (As Above)	hours before measurin	g electrical properties.					
	Dielectric Strength	Meets Initial Values (As Above)							
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes					
	Capacitance Variation	\leq ±2.5% or ±.25 pF, whichever is greater	Step 2: Room Temp	≤ 3 minutes					
Thermal Shock	Q	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes					
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes					
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 hours at roo						
	Appearance	No visual defects	-						
	Capacitance Variation	≤ ±3.0% or ± .3 pF, whichever is greater	Charge device with twi chamber set a						
Load Life	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	for 1000 hou	ırs (+48, -0).					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	temperature before m	for 24 hours					
	Dielectric Strength	Meets Initial Values (As Above)							
	Appearance	No visual defects	4						
	Capacitance Variation	$\leq \pm 5.0\%$ or $\pm .5$ pF, whichever is greater	Store in a test chamber set at 85°C ± 2°C/ 85% 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.						
Load Humidity	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C							
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at room temperature for 24 ± 2 hours before measuring						
	Dielectric Strength	Meets Initial Values (As Above)							





COG (NP0) - Capacitance Range

PREFERRED SIZES ARE SHADED

							d=10				ш						I					
SIZE			LD02			LD	03				LD05					LDO	6					
Solder	ing	Re	eflow/Wa	ave		Reflow	v/Wave			Re	eflow/Wa	ve				Reflow/\	Nave					
Packag			All Pape				Paper				er/Embos				Pa	aper/Eml						
(L) Length	mm (in.)		.00 ± 0.1 040 ± 0.0				± 0.15 ± 0.006)				.01 ± 0.2)79 ± 0.0				(3.20 ± (0.126 ± (
W) Width	mm (in.)		.50 ± 0.1 020 ± 0.0				± 0.15 ± 0.006)				.25 ± 0.2 049 ± 0.0				(1.60 ± 0 0.063 ± 0						
(t) Terminal	mm	0	.25 ± 0.1	5		0.35	± 0.15			0	.50 ± 0.2	5				0.50 ± 0).25					
(1)	(in.) WVDC	(0.0 16	010 ± 0.0 25	50	16	(0.014)	<u>± 0.006)</u> 50	100	16	(0.0 25	020 ± 0.0 50	10)	200	16	25	0.020 ± 0 50	100	200	500			
Сар	0.5	C	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
(pF)	1.0 1.2	C C	C C	C C	G G	G G	G	GG	J	J J	J	J	J	J	J	J J	J J	J J	J			
	1.5	C	C	C	G	G	G	G	J	J	J	J		J	J	J	J	J	J			
	1.8 2.2	C C	C C	C C	G G	G G	G	G	J J	J J	J	J	J	J	J	J J	J J	J J	J			
	2.7 3.3	C C	C C	C C	G G	G G	G	GG	J J	J J	J	J	J J	J	J	J J	J J	J J	J J			
	3.9	c	C	C	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
	4.7 5.6	<u>С</u> С	C C	C C	G G	G G	G G	GG	J J	J J	J	J	J J	J	J	J	J J	J J	J J			
	6.8	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
	8.2 10	C C	C C	C C	G G	G G	G G	GG	J J	J J	J	J J	J J	J	J	J J	J J	J	J J			
	12	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
	15 18	<u>С</u> С	C C	C C	G G	G G	G G	GG	J J	J J	J	J	 	J	J	J J	J J	J	J J			
	22	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
	27 33	<u>С</u> С	C C	C C	G G	G G	G G	GG	J J	J J	J	J	J J	J	J	J J	J J	J J	J			
	39	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
	47 56	<u>С</u> С	C C	C C	G G	G G	G	GG	J J	J J	J	J	 	J	J	J J	J J	J J	J			
	68	С	С	С	G	G	G	G	J	J	J	J	J	J	J	J	J	J	J			
	82 100	C C			G G	G G	G	GG	J J	J J	J	J	J J	J	J	J J	J J	J J	J			
	120 150	C C	C C	C	G	G G	G G	GG	J	J	J	J	J	J	J	J	J J	J	J			
	150	<u>с</u>	C	C C	G	G	G	G	J J	J	J	J	J J	J	J	J J	J	J	J			
	220 270	C C	C C	C C	G G	G G	G G	GG	J J	J J	J	J	J M	J	J	J J	J J	J	M M			
	330	C	C	C	G	G	G	G	J	J	J	J	M	J	J	J	J	J	M			
	390 470	C C	C C	C C	G G	G G	G G	G	J J	J J	J	J	M M	J	J	J J	J J	J	M M			
	560	0			G	G	G		J	J	J	J	M	J	J	J	J	J	М			
	680 820				G G	G G	G		J J	J	J	J		J	J	J J	J J	J M	Р			
	1000				G	G	G		J	J	J	J		J	J	J	J	Q				
	1200 1500					G			J J	J J	J			J	J	J J	J M	Q Q				
	1800								J	J	J			J	J	М	М					
	2200 2700								J J	J J	N N			J	J	M M	P P		1			
	3300								J	J				J	J	M	P P					
	3900 4700								J	J				J	J	M M	P					
	5600 6800													J	J	М			1			
	8200													М	М			\vdash				
Cap (pF)	0.010 0.012													М	М							
L	0.015		Ļ	-		6	I _											\vdash				
	0.018 0.022		-	-1-	\sim	-W-	$\mathbf{\mathbf{x}}$															
	0.027		- 1		\sum	IJ	Ĵ⊤ _											⊢				
	0.033 0.039				\square																	
	0.047		ŀ		a t													⊢−−				
	0.082			1	1		I															
	0.1 WVDC	16	25	50	16	25	50	100	16	25	50	100	200	16	25	50	100	200	500			
	SIZE	10	LD02	30	10		03	100	10	23	LD05	100	20	10	25	50 LD0		30				
Letter	A			E	G		J	К	M		N	P		Q X			-	Z	7			
Max.	0.33	0.5		0.71	0.90	0	0.94	1.02	1.27		1.40	1.52	1.5		2.29	2.54		2.79	1			
Thickness	(0.013)	(0.0		(0.028) (0.035) (0.037) (0.04				(0.040)	(0.05	0) (0	.055)	(0.060)		0.070) (0.090) (0.100) (0.110)								
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COG (NPO) - Capacitance Range

PREFERRED SIZES ARE SHADED





X8R – General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.





X8R – Specifications and Test Methods

Paramet	ter/Test	X8R Specification Limits	Measuring	Conditions				
Operating Temp	perature Range	-55°C to +150°C	Temperature C	cycle Chamber				
Capac	itance	Within specified tolerance	Freg.: 1.0 k	∠U→ ± 10%				
Dissipatio	on Factor	\leq 2.5% for ≥ 50V DC rating \leq 3.5% for 25V DC and 16V DC rating	Voltage: 1.0	Vrms ± .2V				
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roc					
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current) mA (max) h 150% of rated voltage				
	Appearance	No defects	Deflectio	on: 2mm				
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	30 seconds 7 1mm/sec				
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)						
	Insulation Resistance	≥ Initial Value x 0.3	90 1	mm				
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.					
	Appearance	No defects, <25% leaching of either end terminal						
	Capacitance Variation	≤ ±7.5%						
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260° C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.					
	Insulation Resistance	Meets Initial Values (As Above)		g electrical properties.				
	Dielectric Strength	Meets Initial Values (As Above)						
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes				
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes				
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes				
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes				
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro					
	Appearance	No visual defects	-					
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 test chamber set					
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamber and stabilize at roor temperature for 24 ± 2 hours before measuring					
	Dielectric Strength	Meets Initial Values (As Above)						
	Appearance	No visual defects						
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi					
Load	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated					
Humidity	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber temperature an	nd humidity for				
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours bef	fore measuring.				





X8R – Capacitance Range

	SI	ZE			LD0	3			L	D05			LD06	
		WVD	С	2	5V	50V			25V	5	0V	25V		50V
271	Сар	270		(3	G								
331	(pF)	330			3	G			J		J			
471		470		(3	G			J		J			
681		680		(3	G			J		J			
102		1000		(3	G			J		J	J		J
152		1500		(3	G			J		J	J		J
182		1800			3	G			J		J	J		J
222		2200		(3	G			J		J	J		J
272		2700			3	G			J		J	J		J
332		3300		(3	G			J		J	J		J
392		3900			3	G			J		J	J		J
472		4700			3	G			J		J	J		J
562		5600			3	G			J		J	J		J
682		6800			3	G			J		J	J		J
822	Сар	8200			3	G			J		J	J		J
103	(µF)				3	G			J		J	J		J
123		0.012			3	G			J		J	J		J
153		0.015			3	G			J		J	J		J
183		0.018			3	G			J		J	J		J
223		0.022			3	G			J		J	J		J
273		0.027			3	G			J		J	J		J
333		0.033			3	G			J		J	J		J
393		0.039			3	G			J		J	J		J
473		0.047			3	G			J		J	J		J
563		0.056			3				N		N	М		М
683		0.068		(3				N		N	M		M
823		0.082							N		N	M		M
104		0.1							N		N	<u>M</u>		M
124		0.12							N		N	M		М
154		0.15							N		N	<u>M</u>		M
184 224		0.18							N			<u>M</u>		M
274		0.22							N			<u>M</u>		M
334		0.27								_		M		M
334		0.33										M		IVI
474		0.39										M		
684		0.47		+						+		IVI		
824		0.82		+						+				
105		0.82								+				
105		WVDC		2	5V	50V			25V	5	0V	25V		50V
	SI	ZE	0	23	LDO				-	D05	0 0	230	LD06	JU V
	_											1		
Letter	A	C	E	G	J	K		M	N	P	Q	X	Y	Z
Max.	0.33	0.56	0.71	0.90		0.94 1.02 1			1.40 (0.055)	1.52	1.78	2.29	2.54	2.79
Thickness	(0.013)	0.013) (0.022) (0.028)								(0.060)	(0.070)	(0.090)	(0.100)	(0.110)
			PAPER							EMB	OSSED			



X7R – General Specifications





AVX Corporation will support those customers for commercial and military Multilayer Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

LD05 5 С 101 2 В Α Size Voltage Dielectric Capacitance Failure Terminations Packaging Special Capacitance 6.3V = 6 LD03 - 0603 X7R = C Code (In pF) Rate B = 5% min lead 2 = 7" Reel Code Tolerance 10V = Z A = Std. LD04 - 0504* 2 Sig. Digits + $B = \pm .10 \, pF \, (< 10 pF)$ A = Not X = FLEXITERM® 4 = 13" Reel LD05 - 0805 16V = Y Number of Applicable with 5% min Product $C = \pm .25 \, pF \, (< 10 pF)$ **Contact Factory** LD06 - 1206 25V = 3 lead** **Zeros** $D = \pm .50 \, pF \, (< 10 pF)$ For LD10 - 1210 35V = D $F = \pm 1\% (\ge 10 \text{ pF})$ Multiples* 50V = 5LD12 - 1812 **X7R only G = ±2% (≥ 10 pF) LD13 - 1825 100V = 1 J = ±5% 200V = 2 LD14 - 2225 K = ±10% 500V = 7 LD20 - 2220 M = ±20%

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)

See FLEXITERM® section for CV options

10,000

1.000

Not RoHS Compliant

Contact factory for availability of Tolerance Options for Specific Part Numbers. NOTE: Contact factory for non-specified capacitance values.



*LD04 has the same CV ranges as LD03.





△ Capacitance vs. Frequency +30 +20 ∆ Capacitance ſ -10 % -20 -30 1KHz 10 KHz 100 KHz 1 MHz 10 MHz



Variation of Impedance with Chip Size Impedance vs. Frequency 10,000 pF - X7R





Insulation Resistance vs Temperature

Variation of Impedance with Chip Size Impedance vs. Frequency 100,000 pF - X7R





X7R – Specifications and Test Methods

Paramet	ter/Test	X7R Specification Limits	Measuring	Conditions			
Operating Tem	perature Range	-55°C to +125°C	Temperature C	ycle Chamber			
Capac	itance	Within specified tolerance					
Dissipatio	on Factor	≤ 10% for ≥ 50V DC rating ≤ 12.5% for 25V DC rating ≤ 12.5% for 25V and 16V DC rating ≤ 12.5% for ≤ 10V DC rating	Freq.: 1.0 k Voltage: 1.0				
Insulation I	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roc				
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50 Note: Charge device with for 500V	and discharge current mA (max) 150% of rated voltage			
	Appearance	No defects	Deflectio	n: 2mm			
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3				
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)					
	Insulation Resistance	≥ Initial Value x 0.3	90 r	mm			
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.9				
	Appearance	No defects, <25% leaching of either end terminal					
	Capacitance Variation	≤ ±7.5%					
Resistance to Solder Heat	Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2			
	Appearance Capacitance Variation Dissipation Factor Insulation Resistance ability Appearance Capacitance Variation Dissipation	Meets Initial Values (As Above)	hours before measuring	g electrical properties.			
		Meets Initial Values (As Above)					
		No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes			
		≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes			
Thermal Shock		Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes			
		Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes			
		Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro				
		No visual defects					
		≤ ±12.5%	Charge device with 1.5 r test chamber set				
Load Life	Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou				
		≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h				
		Meets Initial Values (As Above)					
	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Store in a test chamber s 5% relative humidi				
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated				
numaity	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.				
	Dielectric Strength	Meets Initial Values (As Above)					





X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

			•					8																						
SIZI	E		LD02	2				LD03	3						LD05							LD	06							
Solder	ing	Re	flow/V	lave			Ref	low/W	/ave					Ref	low/W	ave						Reflow	/Wave	;						
Packad	aina	A	ll Par	ber			A	II Pap	ber				F	Paper	/Emb	osse	d				Par	per/En	nbos	sed						
(L) Length	mm	1.	00 ± 0	.10	1		1.0	60 ± 0	.15					2.0	01 ± 0.	20	-					3.20 ±	0.20							
	(in.) mm		40 ± 0 50 ± 0					63 ± 0 81 ± 0							79 ± 0. 25 ± 0.						(0.126 ± 1.60 ±		3)						
W) Width	(in.)		20 ± 0					32 ± 0							49 ± 0.						(0.063 ±		3)						
(t) Terminal	mm (in.)	0.	25 ± 0 10 ± 0	.15	1			35 ± 0 14 ± 0						0.5	50 ± 0. 20 ± 0.	25						0.50 ± 0.020 ±	0.25							
WVD		16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	20 ± 0.	50	100	200	6.3	10	16	25	50	100	200	500				
Сар	100	10	25	50	0.5	10	10	25	50	100	200	0.5	10	10	25	50	100	200	0.5	10	10	25	50	100	200	300				
(pF)	150																													
N° /	220			С																										
	330			С					G	G	G		J	J	J	J	J	J								K				
	470			С					G	G	G		J	J	J	J	J	J								К				
	680			С					G	G	G		J	J	J	J	J	J								K				
	1000			С					G	G	G		J	J	J	J	J	J								К				
	1500			С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M				
	2200			C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M				
	3300		C	C					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M				
	4700 6800	С	C C	С					G G	G			J	J	J	J J	J	J		J	J J	J	J J	J	J J	M P				
Сар	0.010	<u>с</u>							G	G			J	J	J	J	J	J		J	J	J		J	J	P				
μF)	0.010	c						G	G	0			J	J	J	J	J	J		J	J	J	J	J	M	F				
(µ)	0.013	c						G	G				J	J	J	J	J	N		J	J	J	J	J	M					
	0.022	C						G	G				J	Ĵ	J	J	N			J	J	J	J	J	M					
	0.047	-					G	G	G				J	J	J	J	N			J	J	J	J	J	M					
	0.068						G	G	G				J	J	J	J	N			J	J	J	J	J	Р					
	0.10		C*			G	G	G	G				J	J	J	J	N			J	J	J	J	Р	Р					
	0.15				G	G							J	J	J	Ν	N			J	J	J	J	Q						
	0.22				G	G							J	J	N	Ν	N			J	J	J	J	Q						
	0.33												N	N	N	N	N			J	J	М	Р	Q						
	0.47							J*					N	N	N	N	N			M	M	M	P	Q						
	0.68					J*	J*						N	N N	N N*					M	M	Q Q	Q 0	Q						
	1.0					J	J						IN	IN	IN"					P	Q	Q	ų	Q						
	2.2				J*										P*					0	Q	Q								
	3.3				0										•					Y	<u>ч</u>	Y								
	4.7												P*	P*						0*	0*	0*								
	10											P*	Р							Q*	Q*	Q								
	22		İ				İ		İ								ĺ		Q*											
	47																													
	100		6-	50 60 10 16 05				0-		100	000				07		4.0.0	0.5.5				0-		4.6.5	000	500				
	WVDC	16						25 LD03		100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500				
	SIZE		LD02 LD)						LD05							LD	00							
Letter	A		С	EG					J		K M N P Q						Q		Х		Y		Ζ							
Max.	0.33	0.56 0.71 0.90).94		02 1.27 1.40 1.52 1.78						;	2.29		2.54		2.79									
Thickness	(0.013)														(0.06		(0.07		(0.090)) (0.100)).110)							
	(0.0.0)	PAPER									EMBOSSED																			
																500020														

= Under Development





X7R – Capacitance Range

PREFERRED SIZES ARE SHADED

SIZE	E				LD10					LD	12		LD	13		LD	20		LD	14		
Solder	ing			F	Reflow Only	r				Reflow	v Only		Reflow	/ Only		Reflov	v Only		Reflow	v Only		
Packad	jing			Pap	er/Embos	sed				All Emb	ossed		All Emb	ossed		All Em	bossed		All Emi	bossed		
(L) Length	mm			3	3.20 + 0.20					4.50 ±	0.30		4.50 ±	0.30		5.70 :	± 0.50		5.72 ±	± 0.25		
	(in.)				126 ± 0.00					(0.177 ±)	(0.177 ±			(0.224 :			(0.225 ±			
W) Width	mm (in.)				2.50 ± 0.20 098 ± 0.00					3.20 ±)	6.40 ± (0.252 ±			5.00 : : 0.197 (± 0.40 ± 0.016)		6.35 ± (0.250 ±	± 0.25 ± 0.010)		
(t) Terminal	mm			C	0.50 ± 0.25					0.61 ±	0.36		0.61 ±	0.36		0.64 :	± 0.39		0.64 ±	± 0.39		
WVD	(in.) C	10	16	25	020 ± 0.01 50	0) 100	200	500	50	(0.024 ± 100	200) 500	(0.024 ± 50	100	25	(0.025 :	100	200	(0.025 ± 50	100		
Сар	100																					
(pF)	150																		<u></u>	-		
	220											_				⊥ ≺	\geq	_	7)-	TT I		
	330 470																			¥.		
	680																					
	1000															Ť		T T		1		
	1500	J	J	J	J	J	JM													.		
	2200 3300	 	J	J	J	 	J	M				-										
	4700	J	J	J	J	J	J	M														
	6800	J	J	J	J	J	J	М														
Сар	0.010	J	J	J	J	J	J	М	К	К	K	К	М	М		Х	Х	Х	М	Р		
(µF)	0.015	J	J	J	J	J	J	P	K	K	K	P	M	М		X	X	X	M	P P		
	0.022	 	J	J	J	 	J	Q Q	K K	K K	K K	<u>Р</u> Х	M	M		X X	X X	X X	M M	P		
	0.033	J	J	J	J	J	J	Y Y	ĸ	ĸ	ĸ	Z	M	M		x	x	x	M	P		
	0.068	J	J	J	J	J	М		К	К	К	Z	М	М		Х	Х	Х	М	Р		
	0.10	J	J	J	J	J	М		K	K	K	Z	М	М		X	X	Х	М	Р		
	0.15	J	J	J	J	M P	Z		K K	K K	P P		M M	M M		X X	X X	X X	M M	P P		
	0.22 J J J P Z 0.33 J J J J Q I							K	M	X		M	M		X	x	X	M	P			
	0.47	М	М	M	М	Q			к	Р			м	М		х	X	Х	М	Р		
L	0.68	M	M	P	X	X			M	Q		_	M	Р		X	X		M	Р		
	1.0 1.5	N N	N N	P Z	X Z	Z Z			M Z	X Z			M M	Р		X X	X X		M M	P X		
	2.2	X	X	Z	Z	Z			Z	z			IVI			x	x		M	^		
	3.3	Х	Х	Z	Z				Z							Х	Z					
	4.7	Х	X	Z	Z				Z							x	Z					
	10 22	Z	Z	Z	Z							-			Z	Z	Z					
	47	L	2												2							
	100												50									
0.77	WVDC	10	16	25	50	100	200	500						100	25	50	100	200	50	100		
SIZE	E				LD10		_		LD12					13		LD	20	_	LD	14		
Letter	A			E	G		J	К	M		N	Р	Q		(Y	Z					
Max.	0.33	0.5		0.71	0.90	0.		1.02	1.27		1.40 1.52		1.78	2.		2.54	2.79					
Thickness	(0.013)	(0.0		(0.028)	(0.035)	(0.0	37)	(0.040)	(0.050) (0.0)55)	(0.060)))					
l				PAPER								EMBO	IBOSSED									



X5R – General Specifications





AVX Corporation will support those customers for commercial and military Multilaver Ceramic Capacitors with a termination consisting of 5% minimum lead. This termination is indicated by the use of a "B" in the 12th position of the AVX Catalog Part Number. This fulfills AVX's commitment to providing a full range of products to our customers. AVX has provided in the following pages a full range of values that we are currently offering in this special "B" termination. Please contact the factory if you require additional information on our MLCC Tin/Lead Termination "B" products.

Not RoHS Compliant

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



*LD04 has the same CV ranges as LD03.

NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

TYPICAL ELECTRICAL CHARACTERISTICS







X5R – Specifications and Test Methods

Parame	ter/Test	X5R Specification Limits	Measuring	Conditions				
Operating Tem		-55°C to +85°C	Temperature C	ycle Chamber				
Сарас	itance	Within specified tolerance						
Dissipatio	on Factor	≤ 2.5% for ≥ 50V DC rating ≤ 3.0% for 25V, 35V DC rating ≤ 12.5% Max. for 16V DC rating and lower Contact Factory for DF by PN	Freq.: 1.0 k Voltage: 1.0 For Cap > 10 μF, 0	Vrms ± .2V .5Vrms @ 120Hz				
Insulation	Resistance	10,000MΩ or 500MΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roc					
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50	and discharge current				
	Appearance	No defects	Deflectio	n: 2mm				
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 3	8 0 seconds 7 1mm/sec				
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)						
	Insulation Resistance	≥ Initial Value x 0.3	90 r					
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutection for 5.0 ± 0.1					
	Appearance	No defects, <25% leaching of either end terminal						
	Capacitance Variation	≤ ±7.5%						
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic s seconds. Store at room	temperature for 24 ± 2				
	esistance Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance bility Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Dielectric Strength Appearance Capacitance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Dissipation Factor Insulation Resistance Dielectric Strength Appearance Capacitance Variation Insulation Resistance Insulati Insulation R	Meets Initial Values (As Above)	hours before measuring	g electrical properties.				
		Meets Initial Values (As Above)						
	Appearance	Strength Meets Initial Values (As Above) Appearance No visual defects		30 ± 3 minutes				
		≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes				
Thermal Shock		Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes				
		Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes				
		Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro					
		No visual defects						
		≤ ±12.5%	Charge device with 1.5 chamber set at 85°C (+48, -0). Note: Contac	± 2°C for 1000 hours				
Load Life		≤ Initial Value x 2.0 (See Above)	specification part num < 1.5X rate	bers that are tested at				
		≥ Initial Value x 0.3 (See Above)	Remove from test chamb	Ū				
		Meets Initial Values (As Above)	temperature for $24 \pm 2 h$	ours before measuring.				
	Appearance	No visual defects						
		≤ ±12.5%	Store in a test chamber s 5% relative humidi					
Load		≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated					
Humidity	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at room temperature and humidity for					
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours before measuring.					





X5R – Capacitance Range

PREFERRED SIZES ARE SHADED

					•																																
SIZ	E			LI	D02					L	D03	3					LD	05					LD	06					I	_D10	0				LD	12	
Solder	ring		F	Reflo	w/W	ave				Reflo	w/V	Vave				Re	flow	/Wav	e			Re	eflow	/Wa	ve				Refl	ow/V	Vave						
Packa	ging			All I							Pap				P		r/En			d	Р		er/Er			d		Pa		/Emb		ed					
(L) Length	mm (in)			1.00						1.60			- \				.01 ±						1.20 ±							0 ± 0							
	(in.) mm			.040 0.50		<u>004)</u> 10		\vdash	((0.06			5))79 <u>+</u> .25 ±						126 ±					($\frac{6 \pm 0}{0 \pm 0}$		<u>)</u>		+			
W) Width	(in.)					004)		<u> </u>	((0.032			5))49 ±						063 ±					(8 ± 0		5)		<u> </u>			
(t) Terminal	mm (in.)			0.25 .010		15 006)			(0	0.3 0.01			5)				.50 ±)20 ±).50 ± 020 ±					(0 ± 0 0 ± 0))					
WVD		4					50	4						50	6.3					50	6.3					50	4						50	6.3	10	25	50
Сар	100																																				
(pF)	150 220						С																														
	330						C	-			-	-					-										—'				>		~	γ_γ	N		
	470						c																					-	<		<		_		خ≷	-	
	680						С																						(5	7		L	ノ	Ψ.	
	1000						С																						``	_	l	\downarrow	/			-]
	1500						C																								-	Ŧ					
	2200 3300	-	-	-		-	C C	-		_					-		-							_			—										
	4700					С	U							G																							
	6800					С								G																							
Сар	0.010					С																													\square		
(µF)	0.015					С						G	G	G																							
	0.022			_	C	С		-				G	G	G						N											-	-	-	<u> </u>	\square		
	0.033 0.047				C C	С						G G	G G	G G						N N																	
	0.047				c							G	0	G						N																	
	0.10			С	С	С						G		G				Ν		Ν															\square		
	0.15											G						Ν	Ν																		
	0.22		C*								G	G						N	Ν							Q									\square		
	0.33 0.47	C*	C*								G G	G						N N						Q	Q								x				
	0.47	0	0								G							N						Q	Q								^				
	1.0	C*	C*	C*					G	G	G	J*					Ν	N		P*				Q	Q						Х	X	X		H		
	1.5																																				
	2.2	C*						G*	G*	J*	J*					N	Ν	Ν					Q	Q							Ζ	X			\square		
	3.3 4.7							J* J*	J* J*	J* J*	J*				N N	N N	N*	N*			X X	X X	x	Х						Q	Z						
	4.7							K*	J	J					P	P	P	IN			x	x	x	x					х	Z	Z					Ζ	
	22		F	1											P*						X	X	X	X				Ζ	Z	Z	Z			1	⊢┦		\square
	47																				х							Z*									
	100			10	1.6	0.5	50	L .		10		0.5	0.5	56		10	1.6	0.5	0.5	50		4.0		05	0.5	50	Z*	Z	10	1.6	0-	0-		6.6		0.5	
	WVDC SIZE	4	16.3	-				6.3		16 D0		35	50	6.3	10	16 LD		35	50	6.3	10	16 LD		35	50	4	o.3	10	16 D10		35	50	6.3	10 LD		50	
	SIZE		LD02				_	.00.							03					- 10	00	_			_			<u> </u>					12				
Letter	٨			^		F			0										-					0							_	7		1			
Letter Max.	A 0.33	-		C 56	+	E 0.7		G J 0.90 0.94 1				K M N 1.02 1.27 1.40						<u>Q</u> 1.78					+	Z 2.7		1											
Thickness	(0.013)					(0.02																(0.11															
			0.022) (0.028) (0.028) PAPER																		EMBOSSED				ED						_	•		1			

*Optional Specifications – Contact factory

NOTE: Contact factory for non-specified capacitance values

